



COPY OF PAPERS  
ORIGINALLY FILED

2812  
H/105  
Kozel  
3/26/02

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Charles W.C. Lin

Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA

Serial No.: 09/852,824 Filed: May 10, 2001

Examiner: Unknown Group Art Unit: 2812

Atty. Docket No.: P002-2

TC 2800 MAIL ROOM  
FEB 22 2002

RECEIVED

ASSISTANT COMMISSIONER FOR PATENTS

Washington, D.C. 20231

**INFORMATION DISCLOSURE STATEMENT**

Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98, Applicant hereby provides a copy of the documents identified on the enclosed Form PTO-1449.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, an admission that any of these documents, alone or in any combination, is considered to be material to patentability, an admission that any of these documents is prior art as to the above-identified application, or an admission against interest in any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits. Accordingly, no fee is due. 37 C.F.R. § 1.97(b)(3).



COPY OF PAPERS  
ORIGINALLY FILED

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on January 28, 2002.

*D M Sigmund* 1/28/02  
David M. Sigmund  
Attorney for Applicant

Date of Signature

Respectfully submitted,

*D M Sigmund*

David M. Sigmund  
Attorney for Applicant  
Reg. No. 34,013  
(303) 554-8371  
(303) 554-8667 (fax)